**High Flow ABS, POLYLAC® PA-746M**

**Processing Conditions**

A. Pre-drying 80 ~ 85 °C x 2 ~ 3 hrs
   - depending on
   - a) Humidity
   - b) Ratio of reground resin
   - c) Storage conditions

B. Barrel Setting Profile

![Barrel Setting Profile Diagram]

- MAX(°C) 230 230 220
- MIN(°C) 190 190 180

C. Mold Temperature 30~60 °C
   - depending on
   - a) Thickness
   - b) Dimension
   - c) Gate and runner system

**NOTE:**
1. Keep the resin from dust and contamination during handling and production.
2. Do not retain the hot melt at the barrel for a long time between injection cycles.
3. Temperature setting of manifold system should not exceed 240°C to avoid melt from degraded.

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